A semiconductor dynamic sensor comprising:

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according to semicor a semiconductor sensor chip having a member movable a dynamic force applied thereto, the semiconductor sensor chip outputting a sensor signal in response to an amount of movement of the movable member; and

> substrate for mounting and supporting the semiconductor sensor chip thereon, wherein:

> the semiconductor sensor chip is connected to the substrate via an adhesive film.

> The semiconductor dynamic sensor as in claim 1, further including a package case, wherein:

> the substrate is a semiconductor chip having a circuit for processing the sensor signal;

> the semiconductor sensor chip is connected to a surface of the semiconductor chip having the processing circuit; and

> a second surface of the semiconductor chip having the processing circuit is partially connected to the package case.

> The semiconductor dynamic sensor as in claim 1, wherein:

> the adhesive film is made of a thermosetting resin or a thermoplastic resin.

4. The semiconductor dynamic sensor as in claim 3, wherein:

a thickness of the adhesive film is less than 50. μ m.

5. The semiconductor dynamic sensor as in claim 3, wherein:

an elasticity coefficient of the adhesive film is less than 3,000 mega pascal.

6. The semiconductor dynamic sensor as in claim 1, wherein:

the semiconductor sensor chip is a sensor chip for sensing acceleration.

dynamic sensor having a semiconductor sensor chip and a substrate for mounting the semiconductor sensor chip thereon via an adhesive film, the method comprising steps of

sticking the adhesive film to a semiconductor wafer having a plurality of the sensor chips;

dicing the wafer having a plurality of sensor chips together with the adhesive film into individual sensor chips; and

connecting the sensor chip to the substrate via the adhesive film.

8. The method of manufacturing a semiconductor dynamic sensor as in claim 7, the method further including a step of coating a surface of the substrate, on which the sensor chip is mounted, with a resin material to smooth the surface.

